

SEMICONDUCTOR DEVICE AND PROCESS OF PRODUCTION OF SAME

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ABSTRACT OF THE DISCLOSURE

10 A semiconductor device, in particular a thin
semiconductor package, which reduces and simultaneously
achieves a uniform mounting height, does not require
complicated steps for mounting individual chips, improves
the manufacturing yield, achieves a uniform height of the
semiconductor device without being affected by the
variation in thickness of the chip, and enables execution
15 of an electrical test all together, and a process for
production of the same, wherein a semiconductor is
mounted, with its back surface exposed upward, on the top
surface of an insulating tape substrate having through
holes in the thickness direction, the area around the
20 side surfaces of the semiconductor element is sealed by a
sealing resin layer, metal interconnections formed on the
bottom surface of the tape substrate define the bottom
portions of the through holes of the tape substrate, a
solder resist layer having through holes in the thickness
25 direction covers the bottom surface of the metal
interconnections and the tape substrate, connection
terminals extending downward from the active surface of
the semiconductor element are inserted into the through
holes of the tape substrate, a filler comprised of a
30 conductive material fills the gaps between the connection
terminals and the through holes of the tape substrate,
and the connection terminals and the metal
interconnections are electrically connected.